

## Features

- For Use With:  
Universal  
Rectangular Alu
- Mounting: Adhesive  
Foil
- Thermal Resistance  
14.0°C/W

## RS PRO Heatsinks

RS Stock No.: 7500908



RS PRO Professionally Approved Products bring to you professional quality parts across all product categories. Our product range has been tested by engineers and provides a comparable quality to the leading brands without paying a premium price.

## Product Description

**Push pin type BGA heatsink suitable for surface mount chip cooling and various other applications.**

## General Specifications

For Use With	Universal Rectangular Alu
Material	Aluminium
Mounting	Adhesive Foil
Application	High Power Semiconductor Device, Optoelectronic Device
Finish	Anodized
Notes	<ul style="list-style-type: none"><li>• Thermal Resistance is calculated based on a distributed heat load and vertically mounted fins anodised heatsink with a 60°C temperature.</li><li>• Under general operating conditions the thermal mounting arrangement of the device is not know and therefore the figures should be used as a guide to selection.</li><li>• We recommend that the effectiveness of any heatsink is tested in the specific operating environment in which it will be subjected.</li></ul>

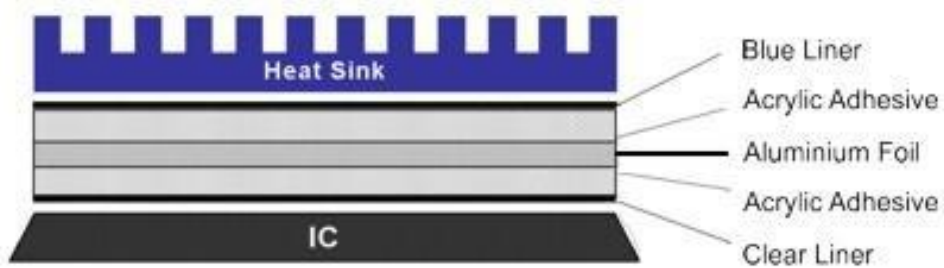
## Mechanical Specifications

Length	20mm
Width	20mm
Height	19.1mm
Dimension	20 x 20 x 19.1mm

## Electrical Specifications

Thermal Resistance	14.0°C/W
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Drawing below is for illustration purposes only. If any further information is required please contact us.



Colour	-	White
Backing Type / Thickness	Mm	Aluminium Foil / 0.10
Adhesive Type / Thickness	Mm	Arylic 0.075 (on clear liner side)
Total Thickness	mm	0,27
Adhesion	Kg/25mm	1,5
Thermal Conductivity	W/m-K	0,95
Thermal Resistance	°C-in <sup>2</sup> /W	0,2
Holding Power@23°C	Hour	>72
Holding Power @ 130°C	Hour	>2